

# Voltage Detector with ON/OFF Control of the Watchdog

## FEATURES

- Detect Voltage Range 1.6 V – 5.0 V in 0.1 V increments
- Accuracy  $\pm 2\%$
- Hysteresis 5% (typical)
- Low Power Consumption  
0.4  $\mu$ A (Detect at  $V_{IN} = 1.0$  V)  
0.6  $\mu$ A (Release at  $V_{IN} = 1.0$  V)
- Operating Voltage Range 1.0 V – 6.0 V
- Detect Voltage Temperature Drift  $\pm 100$  ppm/ $^{\circ}$ C
- Output Configuration - N-channel Open Drain
- Watchdog with ON/OFF Control
- Pre-programmed Release Time of 3.13, 50, 100, 200, and 400 ms
- Pre-programmed Watchdog Time of 50, 100, 200, 400, 800, and 1600 ms
- Operating Ambient Temperature - 40 + 85 $^{\circ}$ C
- Packages : USP-6C and SOT-25
- EU RoHS Compliant, Pb Free

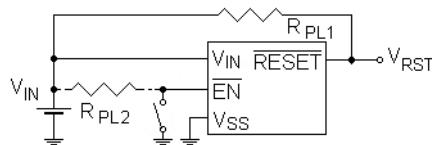
## APPLICATIONS

- Microprocessor reset circuitry
- Memory battery back-up circuits
- Power-on reset circuits
- Power failure detection
- System battery life and charge voltage monitors

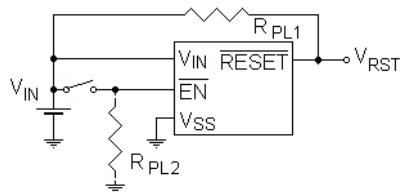
## DESCRIPTION

The IXD5121/22/23/24 are highly precise, low power consumption, CMOS voltage detectors with watchdog function, manufactured using laser trimming technology.

## TYPICAL APPLICATION CIRCUIT



IXD5121/22 Application Circuit (R<sub>PL2</sub> is used with IXD5121 only)



IXD5123/24 Application Circuit (R<sub>PL2</sub> is used with IXD5123 only)

The series consists of a reference voltage source, delay circuit, comparator, and output driver. With the built-in delay circuit, this series does not require any external components.

The RESET output is active LOW, when voltage below  $V_{DFL}$  is detected.

The EN (EN) pin controls the ON/OFF state of the watchdog functions. This pin in an active state disables the watchdog function, while the voltage detector remains operational.

The IXD5122 and IXD5124 series have internal pull-up/down resistors respectively that allows use these IC with watchdog function active, while EN (EN) pins are left open.

The detect voltages are internally fixed in the range of 1.6 V to 5.0 V in 0.1 V increments.

Six watchdog timeout periods are available in a range of 50 ms to 1.6 s.

Five release delay times are available in a range of 3.13 ms to 400 ms.

With low power consumption and high accuracy, the series is suitable for precision mobile equipment.

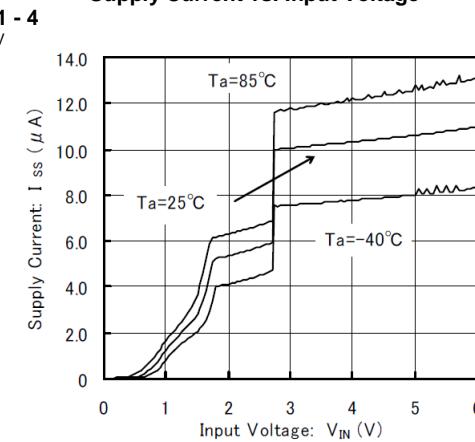
The IXD5121/22/23/24 in ultra small packages are ideally suited for high-density PC boards.

The IXD5121/22/23/24 is available in N-channel open drain output configuration only.

These detectors are available in USP-6C and SOT-25 packages.

## TYPICAL PERFORMANCE CHARACTERISTIC

### Supply Current vs. Input Voltage



## ABSOLUTE MAXIMUM RATINGS

PARAMETER		SYMBOL	RATINGS	UNITS
Input Voltage		V <sub>IN</sub>	-0.3 ~ +7.0	V
Output Current		I <sub>OUT</sub>	20	mA
Output Voltage		V <sub>RST</sub>	-0.3 ~ +7.0	V
EN/(EN) Pin Voltage		V <sub>EN</sub>	-0.3 ~ V <sub>IN</sub> + 0.3 ≤ 7.0	V
WD Pin Voltage		V <sub>WD</sub>	-0.3 ~ +7.0	
Power Dissipation	USP-6C SOT-25	P <sub>D</sub>	120 250	mW
Operating Temperature Range		T <sub>OPR</sub>	-40 ~ +85	°C
Storage Temperature Range		T <sub>STG</sub>	-55 ~ +125	°C

All voltages are in respect to V<sub>SS</sub>

## ELECTRICAL OPERATING CHARACTERISTICS

T<sub>a</sub> = 25 °C

PARAMETER	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNIT	CIRCUIT
Operating Voltage	V <sub>IN</sub>	V <sub>DFL(T)</sub> = 0.8 – 5.0 V <sup>1)</sup>	1.0	6.0	V	①	
Detect Voltage	V <sub>DF</sub>	Watchdog disabled	V <sub>DFL(T)</sub> x 0.98	V <sub>DFL(T)</sub>	V <sub>DFL(T)</sub> x 1.02	V	①
Hysteresis Width	V <sub>HYS</sub>	Watchdog disabled	V <sub>DFL</sub> x 0.02	V <sub>DFL</sub> x 0.05	V <sub>DFL</sub> x 0.08	V	①
Supply Current <sup>2)</sup>	I <sub>SS</sub>	WD = Open	V <sub>IN</sub> = V <sub>DFL</sub> x 0.9 V	5	11	μA	②
			V <sub>IN</sub> = V <sub>DFL</sub> x 1.1 V	10	16		
			V <sub>IN</sub> = 6.0 V	12	18		
Output Current	I <sub>OUT</sub>	V <sub>DS</sub> = 0.5 V N-channel MOSFET	V <sub>IN</sub> = 1.0 V	0.15	0.5	mA	③
			V <sub>IN</sub> = 2.0 V, V <sub>DFL(T)</sub> > 2.0 V	2.0	2.5		
			V <sub>IN</sub> = 3.0 V, V <sub>DFL(T)</sub> > 2.0 V	3.0	3.5		
			V <sub>IN</sub> = 4.0, V <sub>DFL(T)</sub> > 2.0 V	3.5	4.0		
Leakage Current	I <sub>LEAK</sub>	V <sub>IN</sub> = V <sub>RST</sub> = 6.0 V		-0.01	0.1	μA	③
Detect Voltage Temperature Characteristics	$\frac{\Delta V_{DF}}{V_{DF} * \Delta T_{OPR}}$	-40 °C ≤ T <sub>OPR</sub> ≤ 85 °C		± 100		ppm/°C	①
Release Delay Time <sup>1)</sup>	t <sub>DR</sub>	V <sub>DFL</sub> ≤ 1.8 V	2.00	3.13	5.00	ms	④
			37	50	63		
			75	100	125		
			150	200	250		
			300	400	500		
Release Delay Time <sup>2)</sup>	t <sub>DR</sub>	V <sub>DFL</sub> ≥ 1.9 V	2.00	3.13	5.00	ms	④
			37	50	63		
			75	100	125		
			150	200	250		
			300	400	500		
Detect Delay Time <sup>3)</sup>	t <sub>DF</sub>	WD = Open		5.5	33	μs	④
Watchdog Timeout <sup>4)</sup>	t <sub>WD</sub>	V <sub>DFL</sub> ≤ 1.8 V	37	50	63	ms	⑤
			75	100	125		
			150	200	250		
			300	400	500		
			600	800	1000		
			1200	1600	2000		
			37	50	63		
Watchdog Timeout <sup>4)</sup>	t <sub>WD</sub>	V <sub>DFL</sub> ≥ 1.9 V	75	100	125	ms	⑤
			150	200	250		
			300	400	500		
			600	800	1000		
			1200	1600	2000		
Watchdog Minimum Pulse Width	T <sub>WDIN</sub>	V <sub>IN</sub> = 6.0 V, Pulse Amplitude = 6.0 V	300			ns	⑥
WD Pin Voltage Level	High	V <sub>WDH</sub>	V <sub>IN</sub> = V <sub>DFL</sub> x 1.1 V – 6.0 V	V <sub>IN</sub> x 0.7	6.0	V	⑥
	Low	V <sub>WDL</sub>	V <sub>IN</sub> = V <sub>DFL</sub> x 1.1 V – 6.0 V	0	V <sub>IN</sub> x 0.3		
WD Pin Resistance	R <sub>WD</sub>	V <sub>IN</sub> = 6.0 V, R <sub>WD</sub> = V <sub>WD</sub> /I <sub>WD</sub>	300	600	900	kΩ	⑦

## ELECTRICAL OPERATING CHARACTERISTICS (CONTINUED)

T<sub>a</sub> = 25 °C

PARAMETER	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNIT	CIRCUIT
EN Pin Voltage Level	V <sub>ENH</sub>	V <sub>IN</sub> = V <sub>DFL</sub> × 1.1 V – 6.0 V	1.3	V <sub>IN</sub>	0.35	V	⑧
	V <sub>ENL</sub>	V <sub>IN</sub> = V <sub>DFL</sub> × 1.1 V – 6.0 V	0				
EN Pull-up Resistance <sup>3)</sup>	R <sub>EN</sub>	V <sub>IN</sub> = 6.0 V, V <sub>EN</sub> = 0, R <sub>EN</sub> = V <sub>EN</sub> /I <sub>EN</sub>	1.0	1.6	2.4	MΩ	⑨
EN Pull-down Resistance <sup>4)</sup>	R <sub>EN</sub>	V <sub>IN</sub> = 6.0 V, V <sub>EN</sub> = 6.0 V, R <sub>EN</sub> = V <sub>EN</sub> /I <sub>EN</sub>	1.0	1.6	2.4	MΩ	⑨

### NOTE:

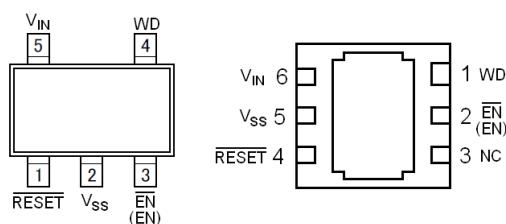
In case, where no EN/ (EN) pin's condition is written in the test condition field, V<sub>EN</sub> = V<sub>IN</sub> for EN pin and V<sub>EN</sub> = 0 V for EN pin.

1) V<sub>DF(T)</sub> is a nominal detect voltage

2) Watchdog is in ON state. At watchdog in off state, Supply current increases by EN/ (EN) pin leakage current, if it is tied to V<sub>IN</sub>.

3) IXD5122 series only

4) IXD5124 series only



The dissipation pad for the USP-6C package should be solder-plated in reference mount pattern and metal masking to enhance mounting strength and heat release. If the pad needs to be connected to other pins, it should be connected to the VSS (No. 5) pin.

## PIN CONFIGURATION

SOT-25  
(TOP VIEW)

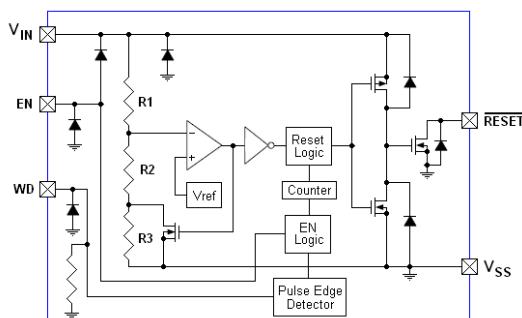
USP-6C  
(BOTTOM VIEW)

## PIN ASSIGNMENT

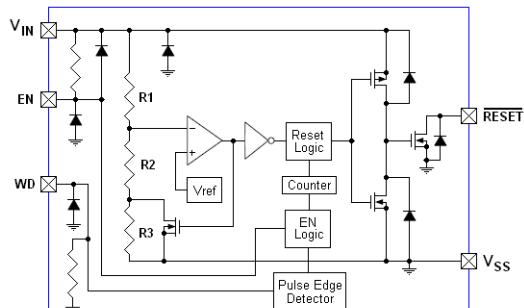
PIN NUMBER	PIN NAME	FUNCTIONS
USP-6C	SOT-25	
4	1	RESET
5	2	V <sub>ss</sub>
2	3	EN (EN)
1	4	WD
6	5	V <sub>IN</sub>
3		NC

## BLOCK DIAGRAMS

IXD5121

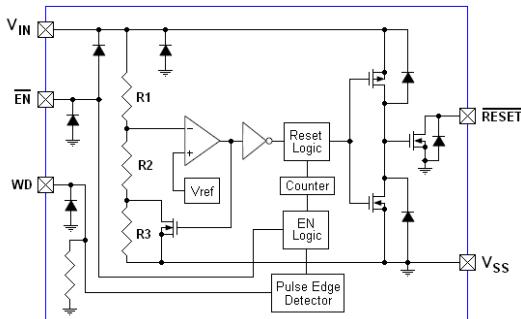


IXD5122

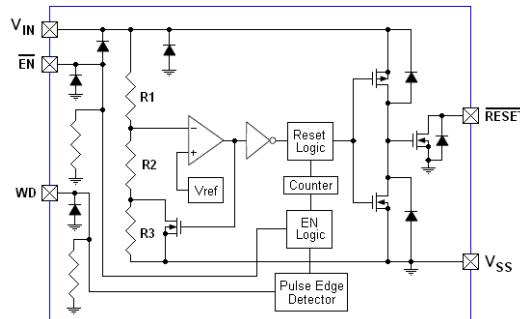


## BLOCK DIAGRAMS (CONTINUED)

IXD5123



IXD5124



Diodes inside the circuits are ESD protection diodes and parasitic diodes.

## BASIC OPERATION

The error amplifier compares the internal reference voltage with the voltage divided by resistors R1, R2, and R3 connected to the V<sub>IN</sub> pin of the IXD5121 – 4 (see block diagrams above). The resulting output signal from the error amplifier activates the watchdog logic, delay circuit, and the output driver. When the V<sub>IN</sub> voltage becomes equal or below detect voltage, the **RESET** output goes from high to low state.

### RESET Pin Output Signal

The **RESET** pin output goes from high to low state whenever the V<sub>IN</sub> pin voltage becomes equal or below the detect voltage. The **RESET** pin remains in low state during the Release Delay Time t<sub>DR</sub> after the V<sub>IN</sub> voltage becomes equal or above the release voltage. When Release Delay Time t<sub>DR</sub> elapsed, the **RESET** pin goes into high state, if no rising or falling signals appear on the WD pin within the watchdog timeout period.

### Hysteresis

When the internal comparator output is high, the N-channel MOSFET transistor connected in parallel to R3 turns ON, activating the hysteresis circuit. The difference between the release and detect voltages represents the hysteresis width, as shown by the following calculations:

$$V_{DFL} (\text{detect voltage}) = (R1+R2+R3) \times V_{ref} / (R2+R3)$$

$$V_{DR} (\text{release voltage}) = (R1+R2) \times V_{ref} / (R2)$$

$$V_{HYS} (\text{hysteresis width}) = V_{DR} - V_{DFL} (V) = V_{DFL} \times 0.05 \text{ (typical)}$$

### Watchdog (WD) Pin

A watchdog timer enables detection of malfunction or “runaway” of the microprocessor. If no rising or falling signals from the microprocessor appear at the WD pin within the Watchdog Timeout period, the **RESET** pin output remains in the low state during the Release Delay Time (t<sub>DR</sub>), and thereafter the **RESET** pin goes to high state.

The WD pin has an internal pull-down resistor connected to the V<sub>SS</sub>. When the watchdog pin is open, or connected to V<sub>SS</sub>, and watchdog is active, a reset signal comes out after the Watchdog Timeout period (t<sub>WD</sub>), which is available at 1.6 s, 800 ms, 400 ms, 200 ms, 100 ms, and 50 ms value.

### EN Pin

If the watchdog function is not used, the EN pin should be in logic low state. This disables watchdog function only, while the detect voltage circuit remains operational.

The EN pin should be logic high to activate watchdog function. The watchdog function activates immediately, when the EN pin voltage goes from low to high level and the input voltage is higher than the release voltage. (Refer to the TIMING DIAGRAM 1-②.)

However, if the EN pin voltage goes high, when the **RESET** pin is in detection state, the **RESET** pin output maintains this state during the Release Delay Time (t<sub>DR</sub>) after V<sub>IN</sub> becomes equal or above V<sub>DR</sub>. (Refer to the TIMING DIAGRAM 1-①.)

A protection diode is connected between the EN and V<sub>IN</sub> pins. If the EN pin voltage exceeds V<sub>IN</sub>, the current will flow to V<sub>IN</sub> through the diode. To avoid any damage to the IC, EN voltage should not exceed maximum ratings (V<sub>SS</sub> -0.3 ~ V<sub>IN</sub> +0.3 V).

#### EN Pin

If the watchdog function is not used, the EN pin should be in logic high state. This disables watchdog function only, while the detect voltage circuit remains operational.

The EN pin should be logic low to activate the watchdog function. The watchdog function activates immediately, when the EN pin voltage goes from high to low level and the input voltage is higher than the release voltage. (Refer to the TIMING DIAGRAM 2-②.)

However, if the EN pin voltage goes low, when the RESET pin is in detection state, the RESET pin output maintains this state during the Release Delay Time ( $t_{DR}$ ) after V<sub>IN</sub> becomes equal or above V<sub>DR</sub>. (Refer to the TIMING DIAGRAM 2-①.)

A protection diode is connected between EN and V<sub>IN</sub> pins. If the EN pin voltage exceeds V<sub>IN</sub>, the current will flow to V<sub>IN</sub> through the diode. To avoiding any damage to the IC, EN pin voltage should not exceed maximum ratings (V<sub>SS</sub> -0.3 ~ V<sub>IN</sub> +0.3 V).

#### Release Delay Time

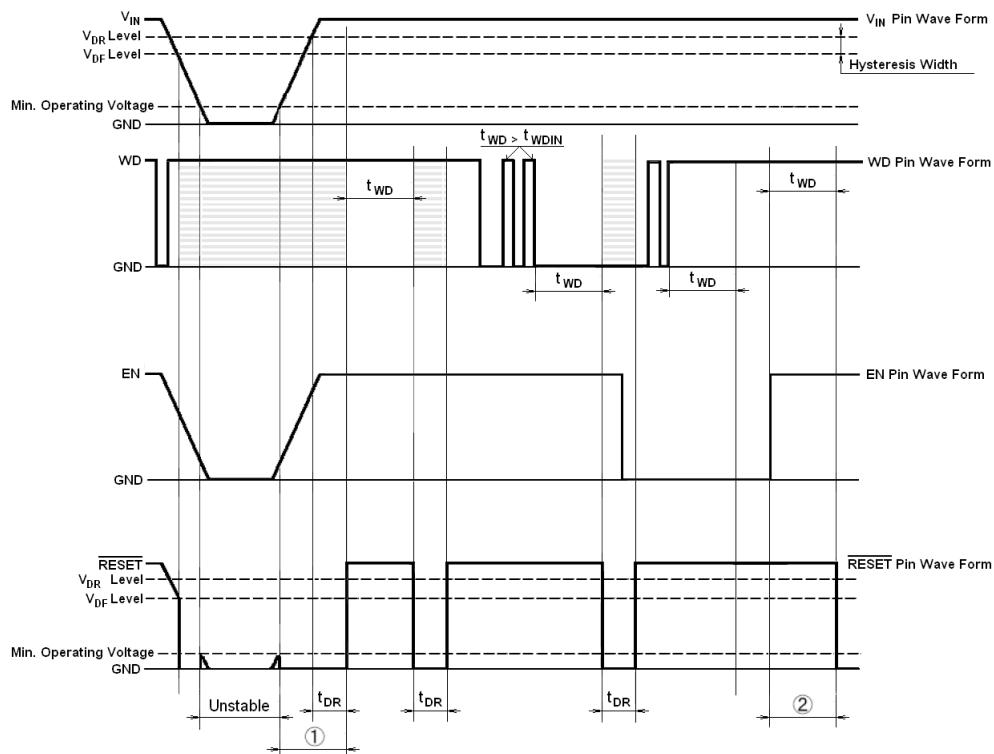
Release Delay Time ( $t_{DR}$ ) is the time from the moment the V<sub>IN</sub> pin becomes equal or above the release voltage V<sub>DR</sub>, until the RESET pin output changes state. When the Watchdog Timeout period expires with no rising signal applied to the WD pin, the same Release Delay Time ( $t_{DR}$ ) should elapse, until the RESET pin output changes state. Five release delay times ( $t_{DR}$ ) are available at 400ms, 200ms, 100ms, 50ms, and 3.13ms.

#### Detect Delay Time

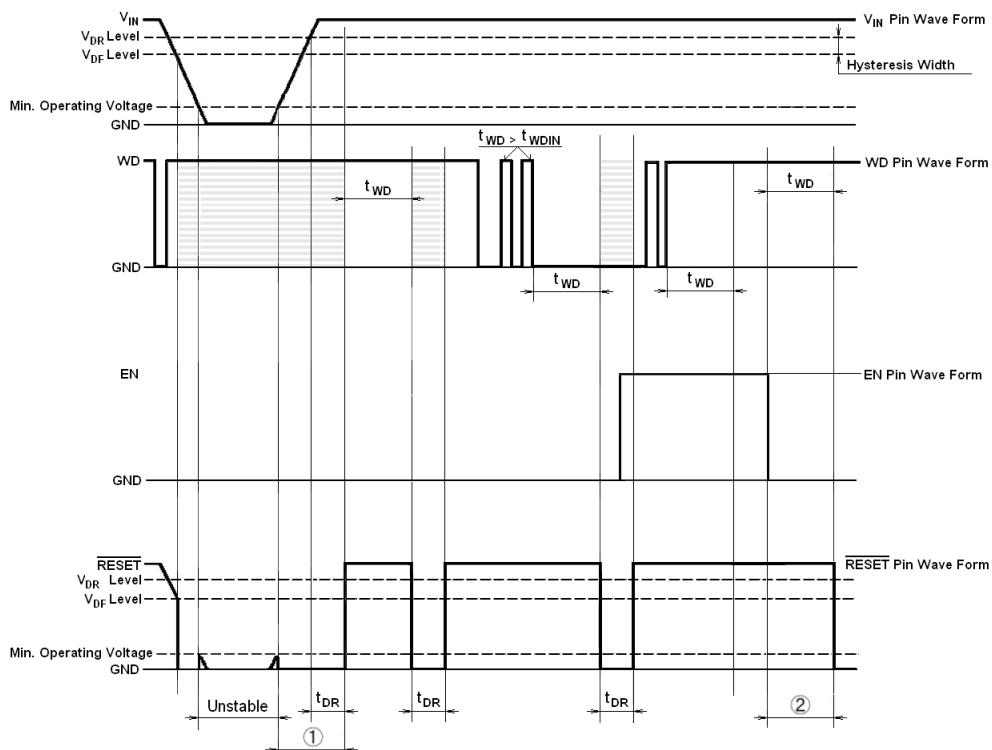
Detect Delay Time ( $t_{DF}$ ) is the time from the moment the V<sub>IN</sub> pin voltage becomes equal or below the detect voltage until the RESET pin output goes into the detection state.

### TIMING DIAGRAMS

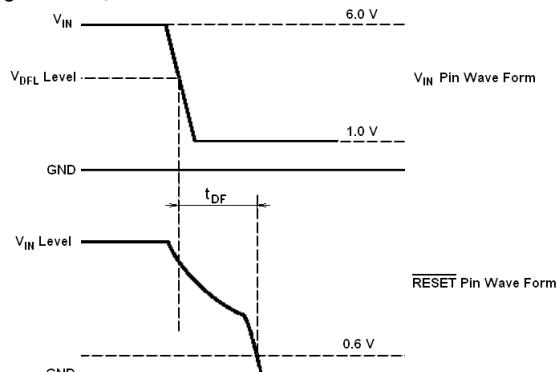
Timing Diagram 1. IXD5121/2 Series



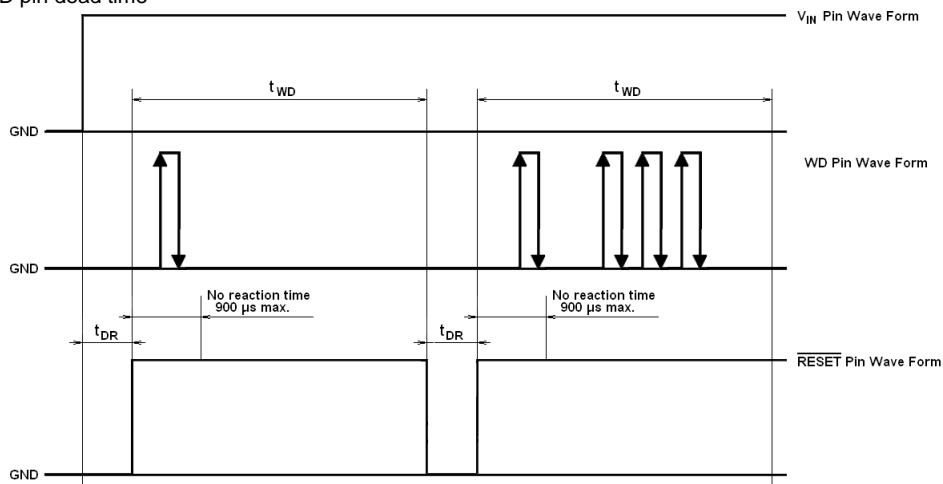
Timing Diagram . IXD5123/4 Series



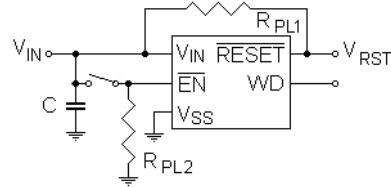
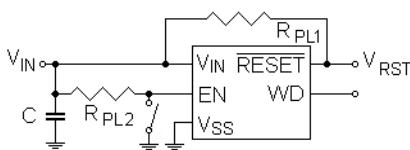
Timing Diagram 3.  $\overline{\text{RESET}}$  Pin output voltage with  $R_{\text{PULL}} = 100 \text{ k}\Omega$



Timing Diagram 4. WD pin dead time



## TYPICAL



## APPLICATION CIRCUIT

IXD5121/22

Resistors RPL2 are used with IXD5121 and IXD5123 series only.

IXD5123/4

## LAYOUT AND USE CONSIDERATIONS

1. The IC may malfunction if absolute maximum ratings are exceeded.
2. High impedance  $V_{IN}$  power supply may cause IC malfunction, if  $V_{IN}$  voltage falls below minimum operating level due current consumption, when IC output changes state. In addition, the  $\overline{RESET}$  pin voltage at "High" state reflects every variations of  $V_{IN}$  voltage.
3. High impedance  $V_{IN}$  power supply may cause IC oscillations, if voltage drop at power supply's internal resistance exceeds IC hysteresis.
4. Note that a rapid and high amplitude fluctuation of the  $V_{IN}$  pin voltage, as well as a power supply noise, may cause a wrong IC operation. The capacitor of 0.22  $\mu F$  between  $V_{IN}$  and GND pins should be used to minimize noise impact.
5. Watchdog Timer has a dead time of less than 900  $\mu s$  after activation. Signals applied to WD pin during this dead time are ignored (see Timing Diagram 4 above).
6. Internal pull-up/ down resistors at EN/ $\overline{EN}$  pins of the IXD5122/4 series allows use watchdog function with these pins open. IXD5121/23 series require EN/ $\overline{EN}$  pins to be pulled up/down respectively to activate watchdog function.

## PIN LOGIC STATE ASSIGNMENT

PIN NAME	CONDITIONS	ASSIGNED LOGIC STATE
$V_{IN}$	$V_{IN} \geq V_{DFL} + V_{HYS}$	H
	$V_{IN} \leq V_{DFL}$	L
EN/ $\overline{EN}$	$V_{EN} \geq 1.3\text{ V}$	H
	$V_{EN} \leq 0.35\text{ V}$	L
WD	$V_{WD} \geq V_{WDH}$ for more than $t_{WD}$	H
	$V_{WD} \leq V_{WDL}$ for more than $t_{WD}$	L
	$V_{WD} = V_{WDH} \rightarrow V_{WDH}$ at 300 ns $\leq t_{WDIN} \leq t_{WD}$	L $\rightarrow$ H
	$V_{WD} = V_{WDL} \rightarrow V_{WDL}$ at 300 ns $\leq t_{WDIN} \leq t_{WD}$	H $\rightarrow$ L

### NOTE:

$V_{DFL}$  - Detect Voltage  
 $V_{HYS}$  - Hysteresis  
 $V_{WDH}$  - WD Pin High Level Voltage  
 $V_{WDL}$  - WD Pin Low Level Voltage  
 $t_{WDIN}$  - WD Pin Input Pulse Width  
 $t_{WD}$  - Watchdog Timeout Period

(See Electrical Characteristics for details of each parameter)

## LOGIC FUNCTION

PIN LOGIC STATES							
IXD5121/22 Series				IXD5123/24 Series			
$V_{IN}$	$V_{EN}$	WD	$V_{RST}$	$V_{IN}$	$V_{EN}$	WD	$V_{RST}^{2)}$
H	H	Static H	Repeating transitions H $\rightarrow$ L $\rightarrow$ H	H	L	Static H	Repeating transitions H $\rightarrow$ L $\rightarrow$ H
H	H	Static L	Repeating transitions H $\rightarrow$ L $\rightarrow$ H	H	L	Static L	Repeating transitions H $\rightarrow$ L $\rightarrow$ H

H	H	Transitions L ↔ H	H	H	L	Transitions L ↔ H	H
H	L	X <sup>1)</sup>	H	H	H	X	H
L	L	X	L	L	H	X	L

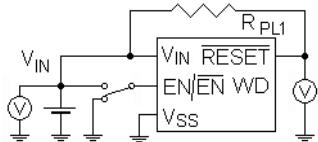
1) X – any logic state

2) V<sub>RST</sub> state is undefined if 0.35 V < V<sub>EN</sub> < 1.3 V

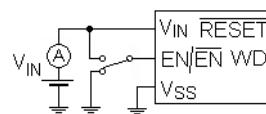
3) EN pin OPEN state for IXD5122 is equal H state, while  $\overline{EN}$  pin OPEN state for IXD5124 is equal L state. IXD5121 and IXD5123 do not allow these pins in OPEN state.

## TEST CIRCUITS

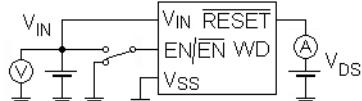
Circuit ①



Circuit ②

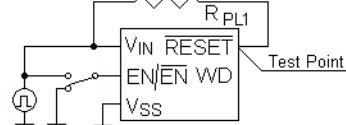


Circuit ③

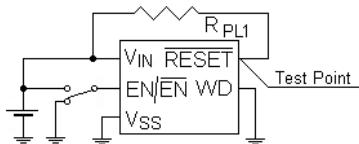


$V_{DS} = 0.5\text{ V}$  ( $V_{DS} = 6.0\text{ V}$  at Leakage Current Measurement)

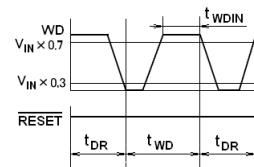
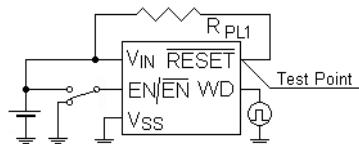
Circuit ④



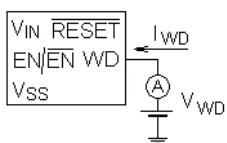
Circuit ⑤



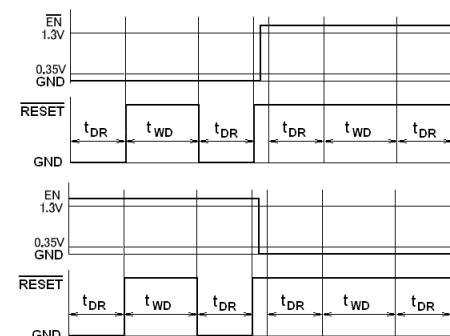
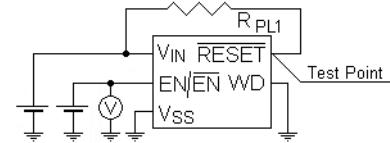
Circuit ⑥



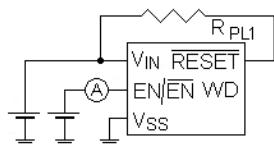
Circuit ⑦



Circuit ⑧



Circuit ⑨



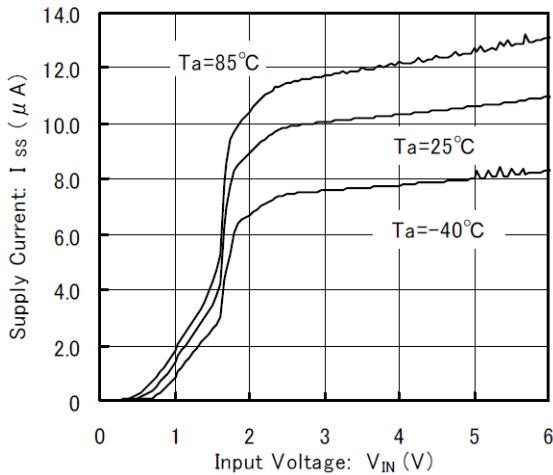
Pull-up Resistor  $R_{PL1} = 100\text{ k}\Omega$

## TYPICAL PERFORMANCE CHARACTERISTICS

(1) Supply Current vs. Input Voltage

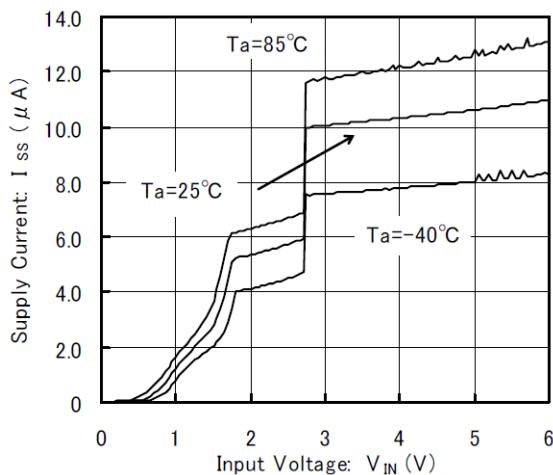
**IXD5121 - 4**

$V_{DF} = 1.6\text{ V}$



**IXD5121 - 4**

$V_{DF} = 2.7\text{ V}$



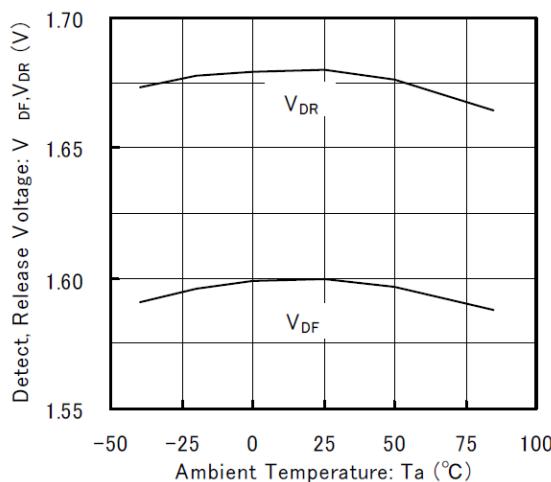
**IXD5121 - 4**

$V_{DF} = 5.0\text{ V}$

(2) Detect/Release Voltage vs. Ambient Temperature

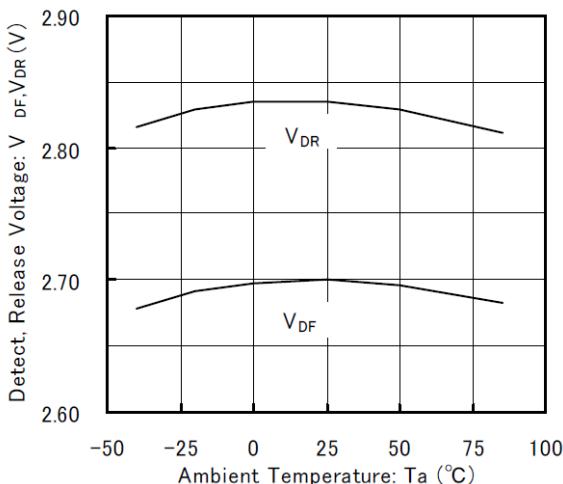
**IXD5121 - 4**

$V_{DF} = 1.6\text{ V}$



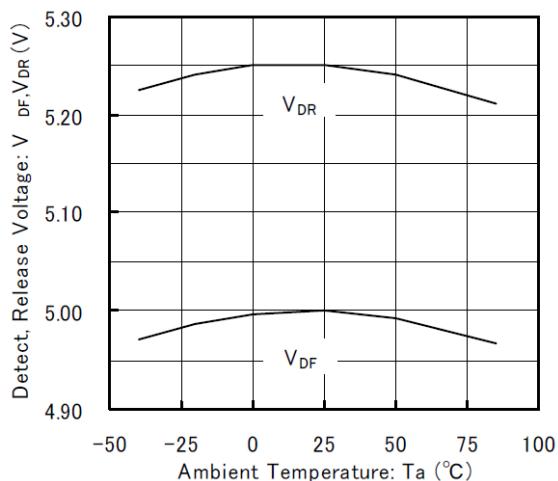
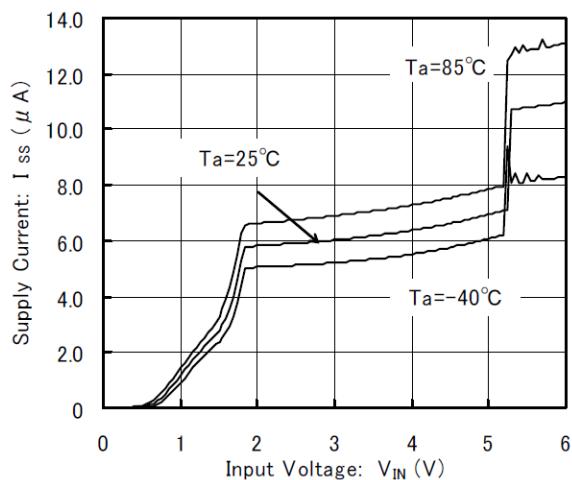
**IXD5121 - 4**

$V_{DF} = 2.7\text{ V}$



**IXD5121 - 4**

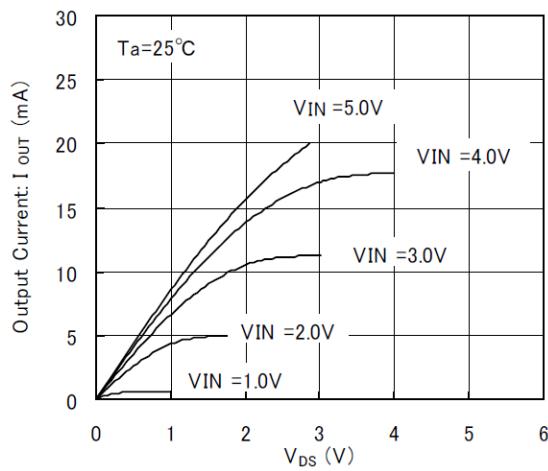
$V_{DF} = 5.0\text{ V}$



## TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

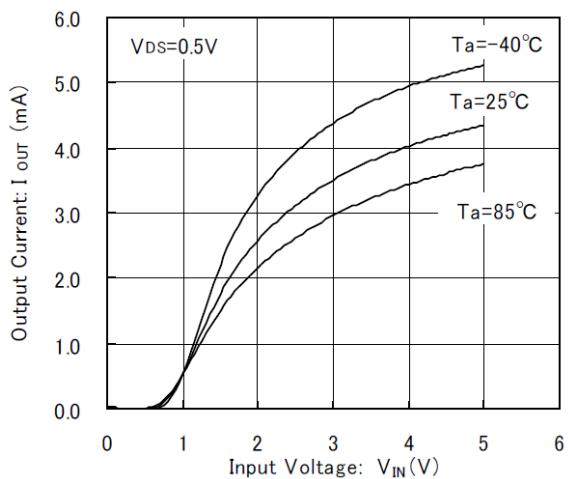
(3) N-channel MOSFET Output Current vs  $V_{DS}$  Voltage

IXD5121 - 4



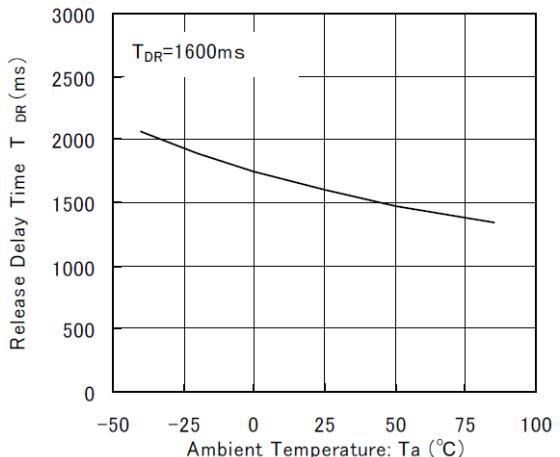
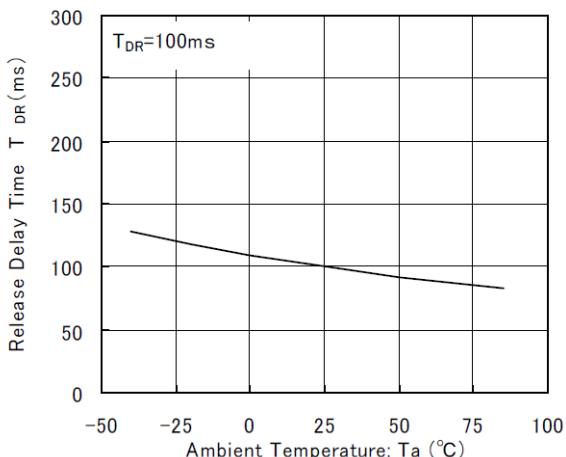
(4) Output Current vs. Input Voltage

IXD5121 - 4



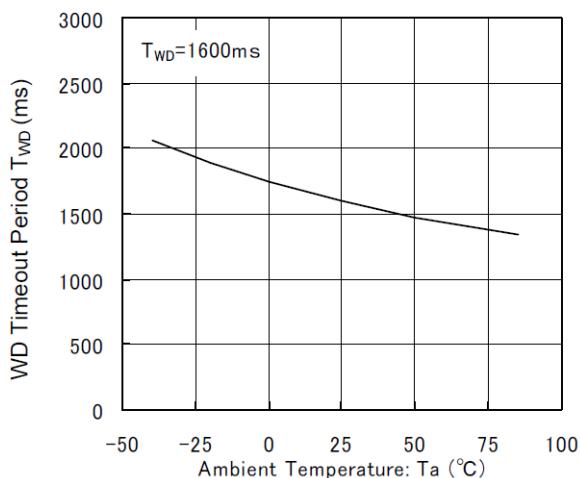
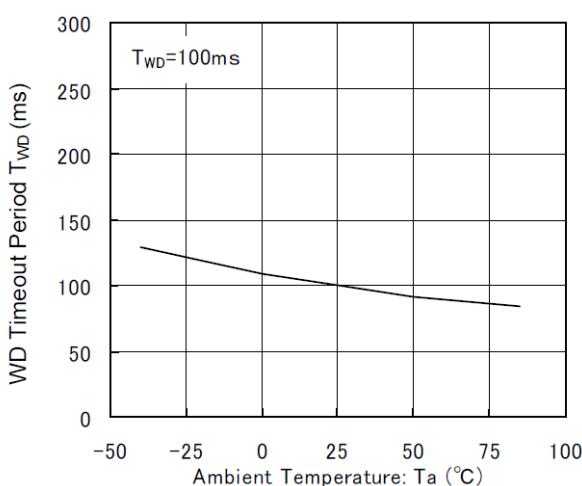
(5) Release Delay Time vs. Ambient Temperature

IXD5121 - 4



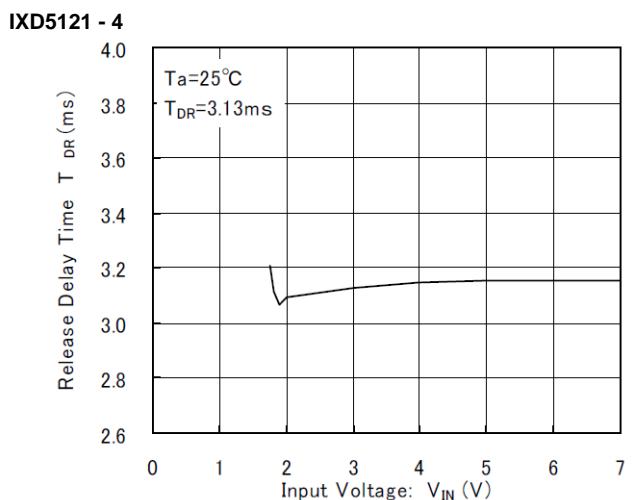
(6) Watchdog Timeout vs. Ambient Temperature

IXD5121 - 4

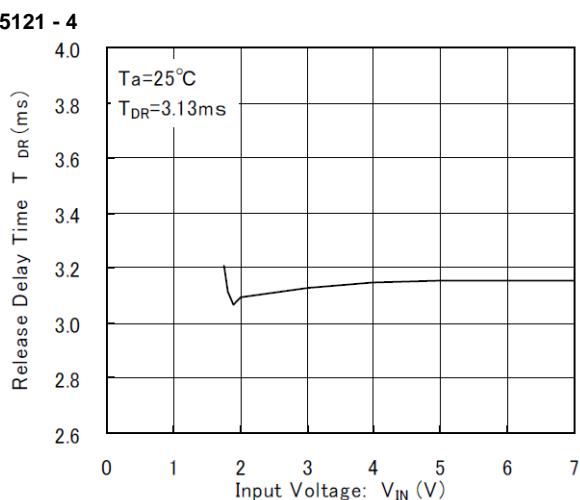


## TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

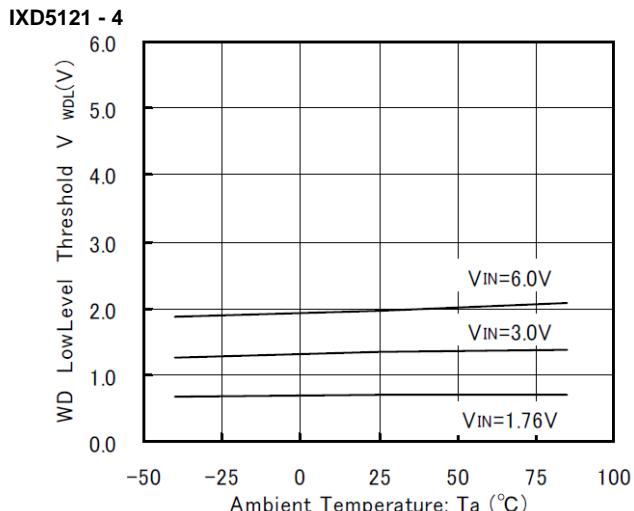
(9) WD Pin LOW Voltage vs. Ambient Temperature



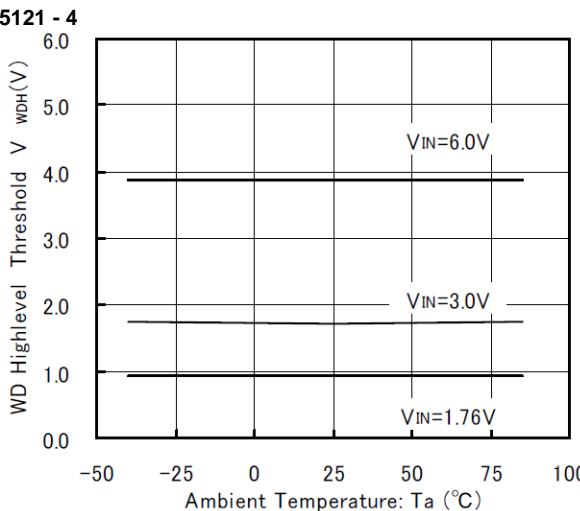
(10) WD Pin HIGH Voltage vs. Ambient Temperature

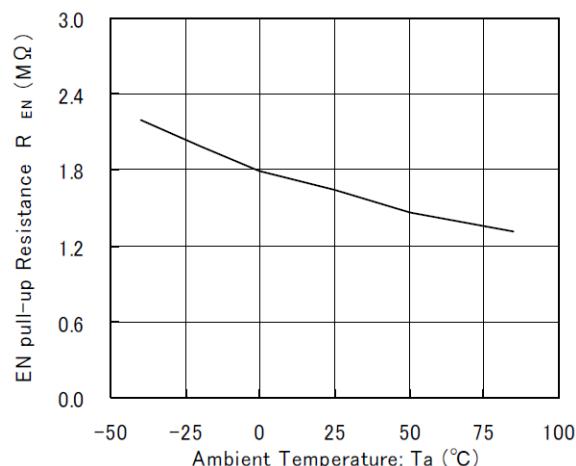
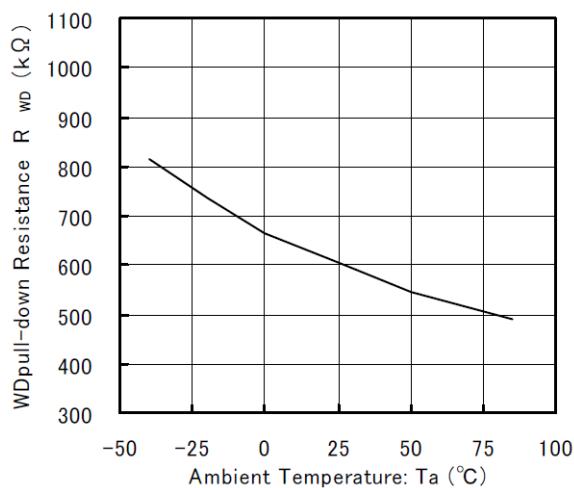


(11) WD Pin Pull-down Resistance vs. Ambient Temperature



(12) EN Pin Pull-up Resistance vs. Ambient Temperature

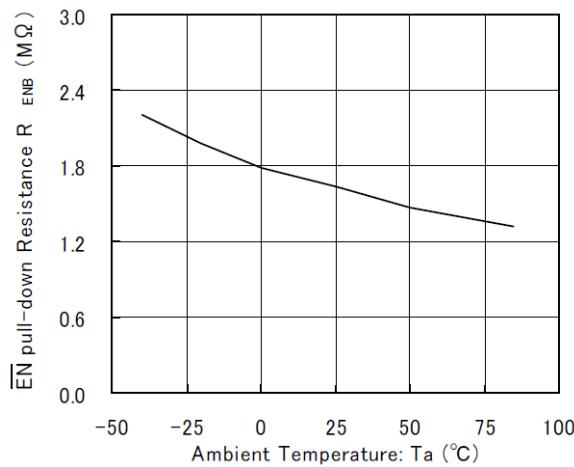




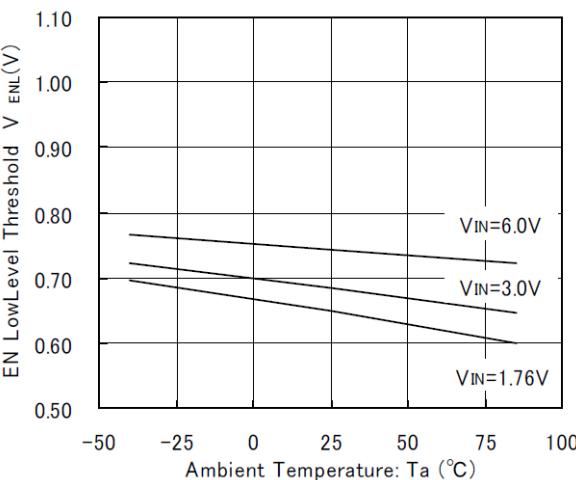
## TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

(13)  $\overline{EN}$  Pin Pull-down Resistance vs Ambient Temperature (14)  $\overline{EN}$  Pin LOW Voltage vs. Ambient Temperature

IXD5121 - 4



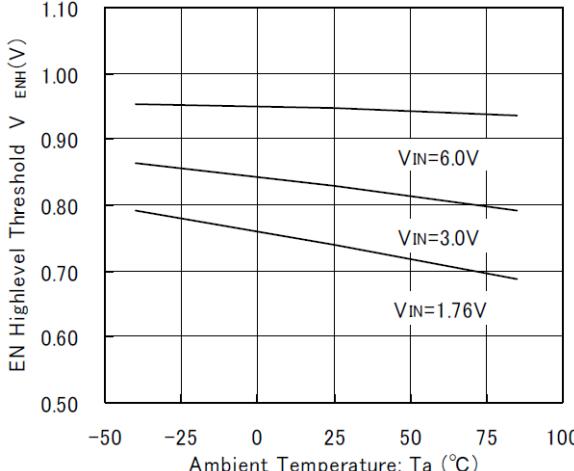
IXD5121 - 4



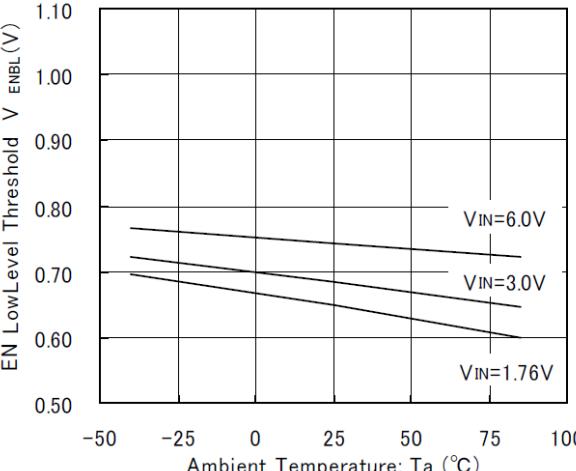
(15) EN Pin HIGH Voltage vs. Ambient Temperature

(16)  $\overline{EN}$  Pin LOW Voltage vs. Ambient Temperature

IXD5121 - 4

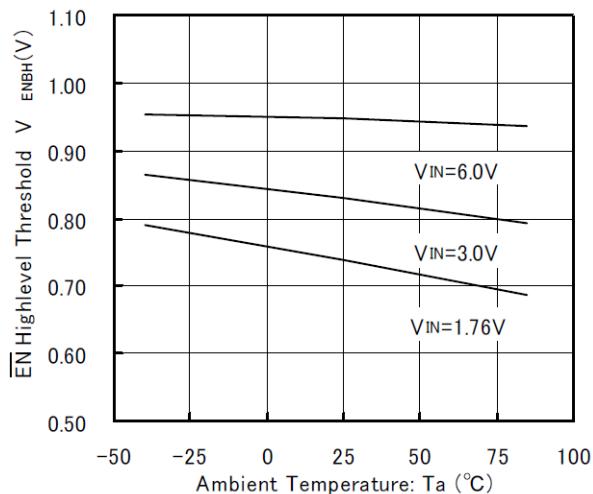


IXD5121 - 4



(17)  $\overline{EN}$  Pin HIGH Voltage vs. Ambient Temperature

IXD5121 - 4



## ORDERING INFORMATION

IXD5121①②③④⑤⑥-⑦ - EN Pin without pull-up resistor  
 IXD5122①②③④⑤⑥-⑦ - EN pin with pull-up resistor  
 IXD5123①②③④⑤⑥-⑦ -  $\overline{\text{EN}}$  pin without pull-down resistor  
 IXD5124①②③④⑤⑥-⑦ -  $\overline{\text{EN}}$  pin with pull-down resistor

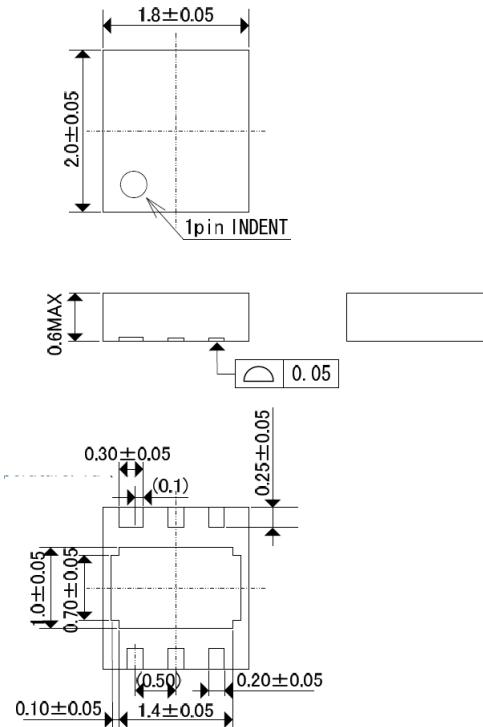
DESIGNATOR	DESCRIPTION	SYMBOL	DESCRIPTION
①	Release Delay Time <sup>1)</sup>	A	3.13 ms
		C	50 ms
		D	100 ms
		E	200 ms
		F	400 ms
②	Watchdog Timeout	2	50 ms
		3	100 ms
		4	200 ms
		5	400 ms
		6	1.6 s
		7	800 ms
③④	Detect Voltage (V <sub>DF</sub> )	16 - 50	Detect Voltage Range: 1.6 V ~ 5.0 V, e.g. 4.2 V - ③ = 4, ④ = 2
⑤⑥-⑦ <sup>(2)</sup>	Packages (Order Unit)	MR	SOT-25 (3000/Reel)
		MR-G	SOT-25 (3000/Reel)
		ER	USP-6C (3000/Reel)
		ER-G	USP-6C (3000/Reel)

### NOTE:

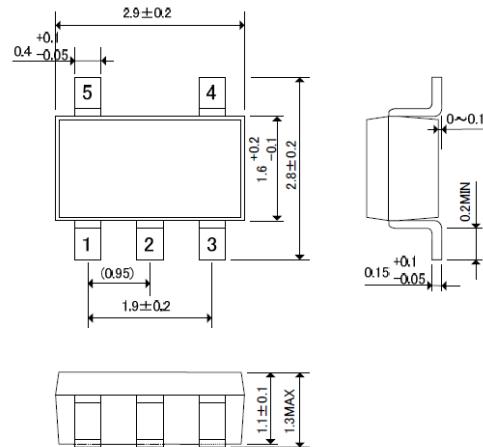
- 1) Release Delay Time should be equal or shorter than watchdog timeout, i.e. if ① = D, acceptable values for ② are from 3 to 7.
- 2) The “-G” suffix denotes Halogen and Antimony free as well as being fully RoHS compliant

## PACKAGE DRAWING AND DIMENSIONS

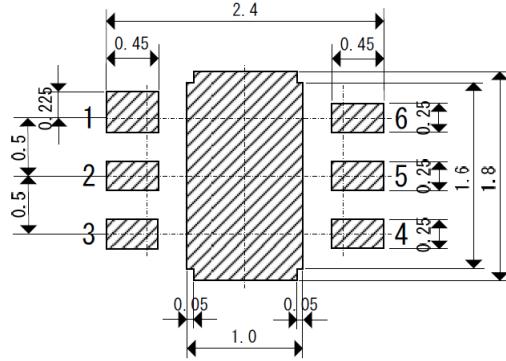
USP-6C, Units: mm



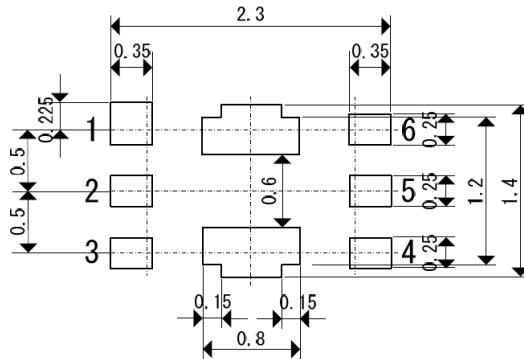
SOT-25, Units: mm



USP-6C Reference Pattern Layout, Units: mm



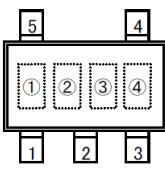
USP-6C Reference Metal Mask Design



## MARKING

SOT-25

① Represents product series



MARK	PRODUCT SERIES
<u>E</u>	IXD5121xxxxxx
<u>F</u>	IXD5122xxxxxx
<u>H</u>	IXD5123xxxxxx
<u>K</u>	IXD5124xxxxxx

② Represents release delay time and watchdog timeout

IXD5121

MARK	RELEASE DELAY TIME	WATCHDOG TIMEOUT	PRODUCT SERIES
0	3.13 ms	50 ms	IXD5121A2****
1	3.13 ms	100 ms	IXD5121A3****
2	3.13 ms	200 ms	IXD5121A4****
3	3.13 ms	400 ms	IXD5121A5****
4	3.13 ms	800 ms	IXD5121A7****
5	3.13 ms	1.6 s	IXD5121A6****
6	50 ms	50 ms	IXD5121C2****
7	50 ms	100 ms	IXD5121C3****
8	50 ms	200 ms	IXD5121C4****
9	50 ms	400 ms	IXD5121C5****
A	50 ms	800 ms	IXD5121C7****
B	50 ms	1.6 s	IXD5121C6****
H	100 ms	100 ms	IXD5121D3****
C	100 ms	200 ms	IXD5121D4****
L	100 ms	400 ms	IXD5121D5****
D	100 ms	800 ms	IXD5121D7****
M	100 ms	1.6 s	IXD5121D6****
E	200 ms	200 ms	IXD5121E4****
R	200 ms	400 ms	IXD5121E5****
F	200 ms	800 ms	IXD5121E7****
S	200 ms	1.6 s	IXD5121E6****
T	400 ms	400 ms	IXD5121F5****
K	400 ms	800 ms	IXD5121F7****
U	400 ms	1.6 s	IXD5121F6****

IXD5122 -4

MARK	RELEASE DELAY TIME	WATCHDOG TIMEOUT	PRODUCT SERIES
N	3.13 ms	50 ms	IXD512*A2****
P	3.13 ms	100 ms	IXD512*A3****
R	3.13 ms	200 ms	IXD512*A4****
S	3.13 ms	400 ms	IXD512*A5****
T	3.13 ms	800 ms	IXD512*A7****
U	3.13 ms	1.6 s	IXD512*A6****
V	50 ms	50 ms	IXD512*C2****
X	50 ms	100 ms	IXD512*C3****
Y	50 ms	200 ms	IXD512*C4****
Z	50 ms	400 ms	IXD512*C5****
A	50 ms	800 ms	IXD512*C7****
B	50 ms	1.6 s	IXD512*C6****
A	100 ms	100 ms	IXD512*D3****
C	100 ms	200 ms	IXD512*D4****
B	100 ms	400 ms	IXD512*D5****
D	100 ms	800 ms	IXD512*D7****
C	100 ms	1.6 s	IXD512*D6****
D	200 ms	200 ms	IXD512*E4****
E	200 ms	400 ms	IXD512*E5****
H	200 ms	800 ms	IXD512*E7****
F	200 ms	1.6 s	IXD512*E6****
K	400 ms	400 ms	IXD512*F5****
M	400 ms	800 ms	IXD512*F7****
L	400 ms	1.6 s	IXD512*F6****

## MARKING (CONTINUED)

SOT-25

③ Represents detect voltage

MARK	DETECT VOLTAGE (V)	PRODUCT SERIES
F	1.6	IXD5121xx16xx
H	1.7	IXD5121xx17xx
K	1.8	IXD5121xx18xx
L	1.9	IXD5121xx19xx
M	2.0	IXD5121xx20xx
N	2.1	IXD5121xx21xx
P	2.2	IXD5121xx22xx
R	2.3	IXD5121xx23xx
S	2.4	IXD5121xx24xx
T	2.5	IXD5121xx25xx
U	2.6	IXD5121xx26xx
V	2.7	IXD5121xx27xx
X	2.8	IXD5121xx28xx
Y	2.9	IXD5121xx29xx
Z	3.0	IXD5121xx30xx
0	3.1	IXD5121xx31xx
1	3.2	IXD5121xx32xx
2	3.3	IXD5121xx33xx
3	3.4	IXD5121xx34xx
4	3.5	IXD5121xx35xx
5	3.6	IXD5121xx36xx
6	3.7	IXD5121xx37xx
7	3.8	IXD5121xx38xx
8	3.9	IXD5121xx39xx
9	4.0	IXD5121xx40xx
A	41	IXD5121xx41xx
B	4.2	IXD5121xx42xx
C	4.3	IXD5121xx43xx
D	4.4	IXD5121xx44xx
E	4.5	IXD5121xx45xx
F	4.6	IXD5121xx46xx
H	4.7	IXD5121xx47xx
K	4.8	IXD5121xx48xx
L	4.9	IXD5121xx49xx
M	5.0	IXD5121xx50xx

MARK	DETECT VOLTAGE (V)	PRODUCT SERIES
H	1.6	IXD512xxx16xx
K	1.7	IXD512xxx17xx
L	1.8	IXD512xxx18xx
M	1.9	IXD512xxx19xx
N	2.0	IXD512xxx20xx
P	2.1	IXD512xxx21xx
R	2.2	IXD512xxx22xx
S	2.3	IXD512xxx23xx
T	2.4	IXD512xxx24xx
U	2.5	IXD512xxx25xx
V	2.6	IXD512xxx26xx
X	2.7	IXD512xxx27xx
Y	2.8	IXD512xxx28xx
Z	2.9	IXD512xxx29xx
0	3.0	IXD512xxx30xx
1	3.1	IXD512xxx31xx
2	3.2	IXD512xxx32xx
3	3.3	IXD512xxx33xx
4	3.4	IXD512xxx34xx
5	3.5	IXD512xxx35xx
6	3.6	IXD512xxx36xx
7	3.7	IXD512xxx37xx
8	3.8	IXD512xxx38xx
9	3.9	IXD512xxx39xx
A	4.0	IXD512xxx40xx
B	41	IXD512xxx41xx
C	4.2	IXD512xxx42xx
D	4.3	IXD512xxx43xx
E	4.4	IXD512xxx44xx
F	4.5	IXD512xxx45xx
H	4.6	IXD512xxx46xx
K	4.7	IXD512xxx47xx
L	4.8	IXD512xxx48xx
M	4.9	IXD512xxx49xx
N	5.0	IXD512xxx50xx

④ Represents production lot number

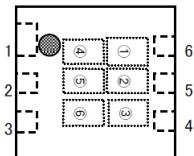
0 to 9 and A to Z and inverted 0 to 9 and A to Z repeated. (G, I, J, O, Q, W excluded.)

## MARKING (CONTINUED)

USP-6C

① Represents product series

MARK	PRODUCT SERIES
P	IXD5121xxxxxx
K	IXD5122xxxxxx
R	IXD5123xxxxxx
U	IXD5124xxxxxx



② Represents release delay time

MARK	RELEASE DELAY TIME	PRODUCT SERIES
A	3.13 ms	IXD512xAxxxx
C	50 ms	IXD512xCxxxx
D	100 ms	IXD512xDxxxx
E	200 ms	IXD512xExxxx
F	400 ms	IXD512xFxxxx

③ Represents watchdog timeout

MARK	WATCHDOG TIMEOUT	PRODUCT SERIES
2	50 ms	IXD512xx2xxx
3	100 ms	IXD512xx3xxx
4	200 ms	IXD512xx4xxx
5	400 ms	IXD512xx5xxx
7	800 ms	IXD512xx7xxx
6	1.6 s	IXD512xx6xxx

④⑤ Represents detect voltage

MARK	DETCT VOLTAGE, V	PRODUCT SERIES
④	⑤	
3	3	IXD512xxx33x
5	0	IXD512xxx50x

④ Represents production lot number

0 to 9 and A to Z repeated. (G, I, J, O, Q, W excluded.)

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